

N-Channel 100 V (D-S) MOSFET

PRODUCT SUMMARY

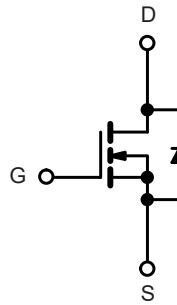
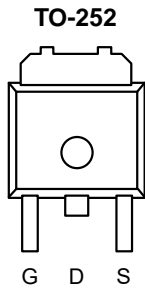
BV _{oss}	100V
R _{DS(on)(MAX.)}	0.052Ω
I _D	30A

FEATURES

- TrenchFET[®] Power MOSFETS
- 175 °C Junction Temperature
- Low Thermal Resistance Package



RoHS*
COMPLIANT



N-Channel MOSFET

Absolute Maximum Ratings (T_c = 25 °C, unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V _{DS}	100	V
Gate-Source Voltage	V _{GS}	±20	V
Continuous Drain Current@10V	I _D	T _c = 25 °C	30
		T _c = 100 °C	13
Pulsed Drain Current	I _{DM}	80	A
Single Pulse Avalanche Energy	E _{AS}	30	mJ
Total Power Dissipation	P _D	L = 0.1 mH	30
		T _c = 25 °C	41.6
Operating Junction and Storage Temperature Range	T _J , T _{STG}	-55 to +175	°C

Thermal Characteristics

Parameter	Symbol	LIMIT.	Unit
Thermal resistance, junction-to-case	R _{θJC}	3.6	°C/W

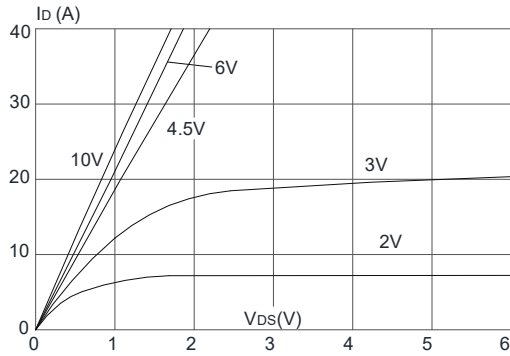
Electrical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{ V}, I_D = 250\ \mu\text{A}$	100	-	-	V
Gate-body Leakage current	I_{GSS}	$V_{DS} = 0\text{ V}, V_{GS} = \pm 20\text{ V}$	-	-	± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$T_J = 25^\circ\text{C}$ $V_{DS} = 100\text{ V}, V_{GS} = 0\text{ V}$	-	-	1	μA
Gate-Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\ \mu\text{A}$	1		2.5	V
Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS} = 10\text{ V}, I_D = 10\text{ A}$	-	0.040	0.052	Ω
		$V_{GS} = 4.5\text{ V}, I_D = 6\text{ A}$	-	0.045	0.058	
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{DS} = 25\text{ V}, V_{GS} = 0\text{ V}, f = 1\text{ MHz}$	-	1966	-	pF
Output Capacitance	C_{oss}		-	92	-	
Reverse Transfer Capacitance	C_{rss}		-	76	-	
Switching Characteristics						
Total Gate Charge	Q_g	$V_{GS} = 4.5\text{ V}, V_{DS} = 80\text{ V}, I_D = 20\text{ A}$	-	22	-	nC
Gate-Source Charge	Q_{gs}		-	3.3	-	
Gate-Drain Charge	Q_{gd}		-	16	-	
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 80\text{ V}, I_D = 20\text{ A}, V_{GEN} = 4.5\text{ V},$ $R_G = 3.1\ \Omega$	-	13	-	nS
Rise Time	t_r		-	93	-	
Turn-Off Delay Time	$t_{d(off)}$		-	42	-	
Fall Time	t_f		-	73	-	
Drain-Source Body Diode Characteristics						
Diode Forward Voltage	V_{SD}	$I_S = 20\text{ A}, V_{GS} = 0\text{ V}$	-	-	1.2	V
Continuous Source-Drain Diode Current	I_S	$T_J = 25^\circ\text{C}$	-	-	30	A
Pulse Diode Forward Current	I_{SM}		-	-	80	
Reverse Recovery Time	t_{rr}	$T_J = 25^\circ\text{C}, I_F = 20\text{ A}, di/dt = 100\text{ A}/\mu\text{s}$	-	66	-	ns
Reverse Recovery Charge	Q_{rr}		-	154	-	nC

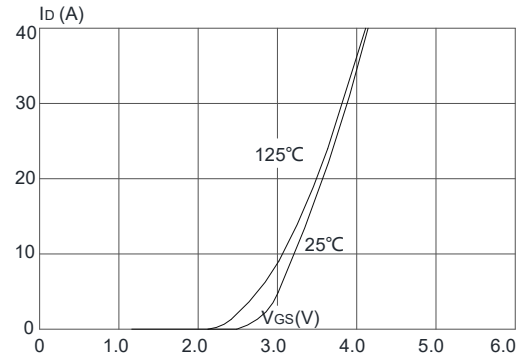
Notes:

- Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
- EAS condition : $T_J = 25^\circ\text{C}, V_{DD} = 50\text{ V}, V_G = 10\text{ V}, L = 0.5\text{ mH}, R_G = 25\ \Omega, I_{AS} = 11\text{ A}$.
- Pulse Test: Pulse Width $\leq 300\ \mu\text{s}$, Duty Cycle $\leq 0.5\%$

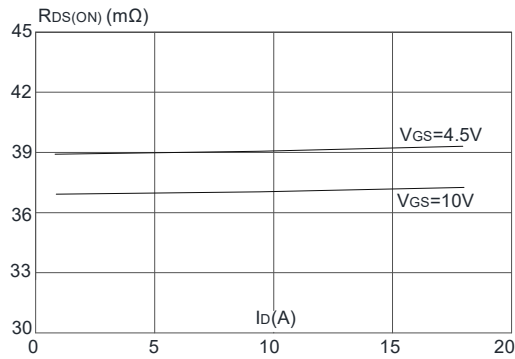
TYPICAL CHARACTERISTICS (25 °C unless noted)



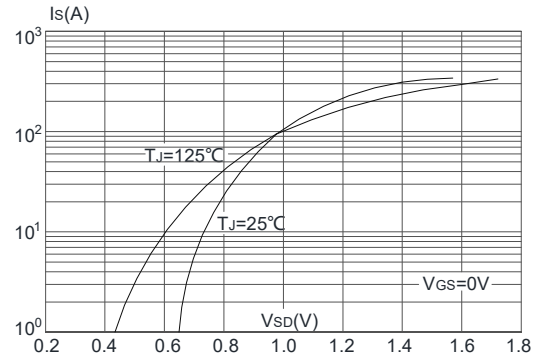
Output Characteristics



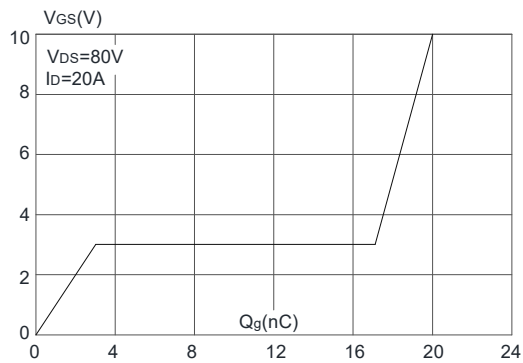
Typical Transfer Characteristics



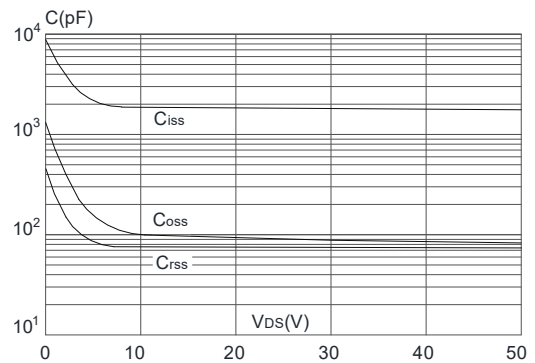
On-resistance vs. Drain Current



Body Diode Characteristics

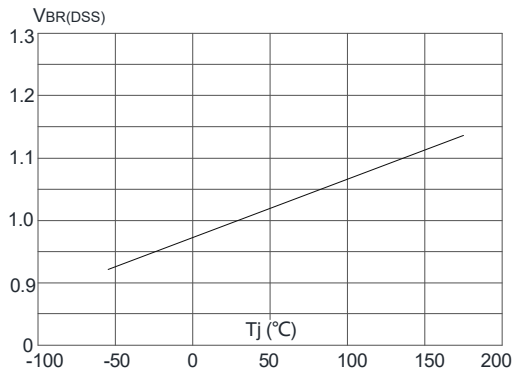


Gate Charge Characteristics

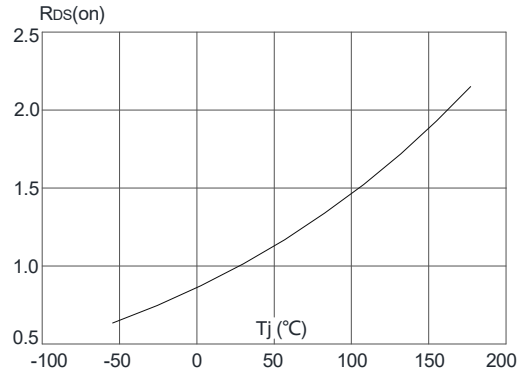


Capacitance Characteristics

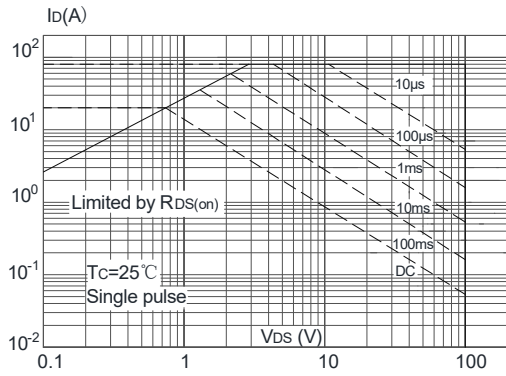
TYPICAL CHARACTERISTICS (25 °C unless noted)



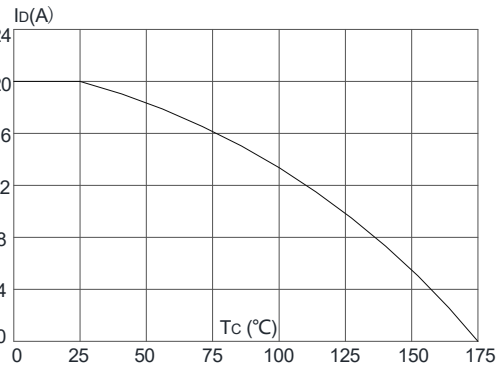
Normalized Breakdown Voltage vs. Junction Temperature



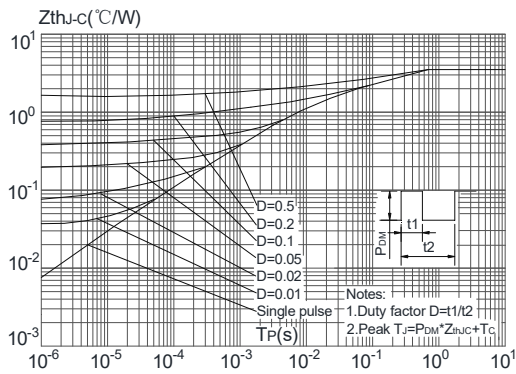
Normalized on Resistance vs. Junction Temperature



Maximum Safe Operating Area



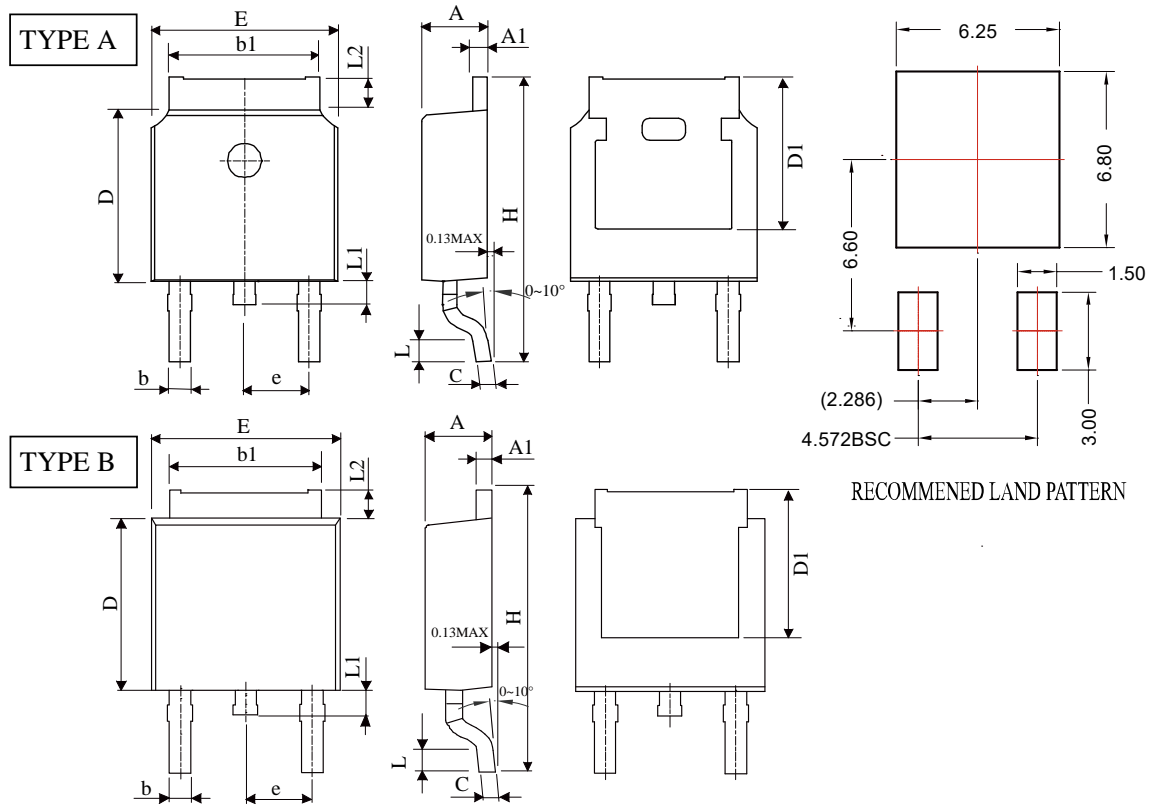
Maximum Continuous Drain Current vs. Case Temperature



Maximum Effective Transient Thermal Impedance, Junction-to-Case

TO-252

Unit: mm



SYMBOLS	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	2.20	2.40	0.087	0.094
A1	0.45	0.89	0.018	0.035
b	0.50	0.90	0.019	0.035
b1	4.95	5.59	0.195	0.220
C	0.40	0.61	0.016	0.024
D	5.40	6.63	0.213	0.261
E	6.05	7.10	0.238	0.280
e	1.98	2.59	0.078	0.102
H	8.80	10.6	0.346	0.417
L	0.25	1.350	0.010	0.053
L1	0.50	1.20	0.020	0.047
L2	0.70	1.78	0.028	0.070
DI	5.00	5.60	0.197	0.220